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Patent Docket # 5123-27RCE

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of
Bassel H. DAOUD et al.
Serial No.: 09/497,045 ✓
Filed: February 02, 2000
For: Mold Incorporating A Heat Source And
Apparatus And Method For Using Such Molds

Examiner: Halpern, Mark
Group Art: 1731 ✓

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June 24, 2003
(Date of Deposit)

Edward M. Weisz
Name of applicant, assignee or Registered Representative
Signature
June 24, 2003
Date of Signature

Mail Stop Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REVISED AMENDMENT

SIR:

Responsive to the Office Action dated January 15, 2003, and to the June 11, 2003 Notice of Non-Compliant Amendment, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 10 of this paper.

Remarks begin on page 14 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 11 of this paper.

Remarks begin on page 15 of this paper.